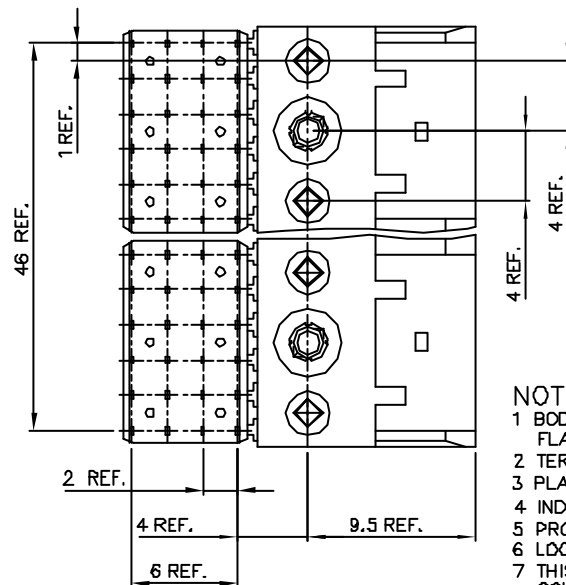
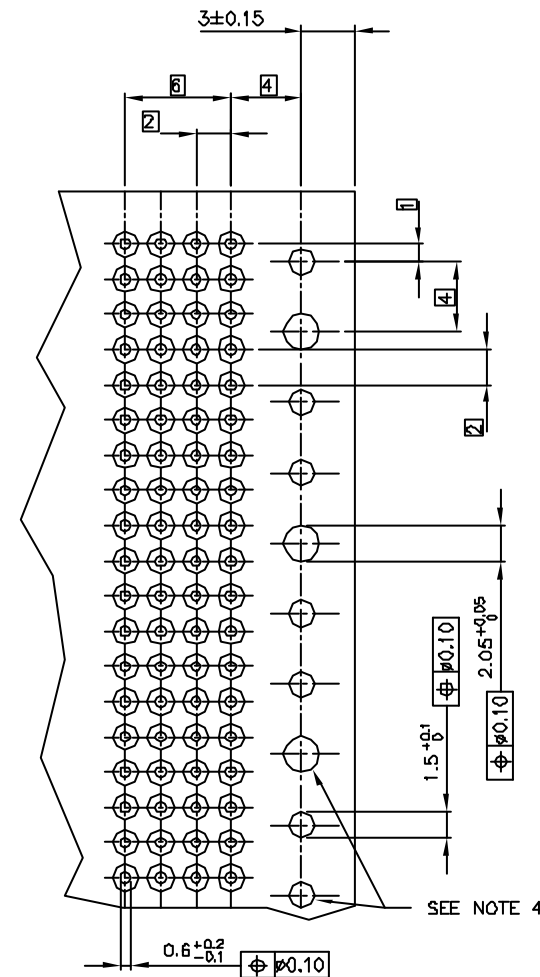
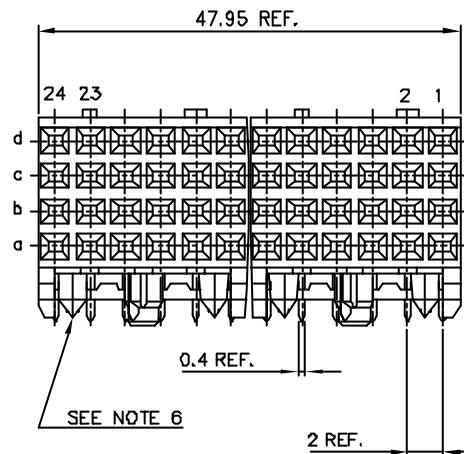
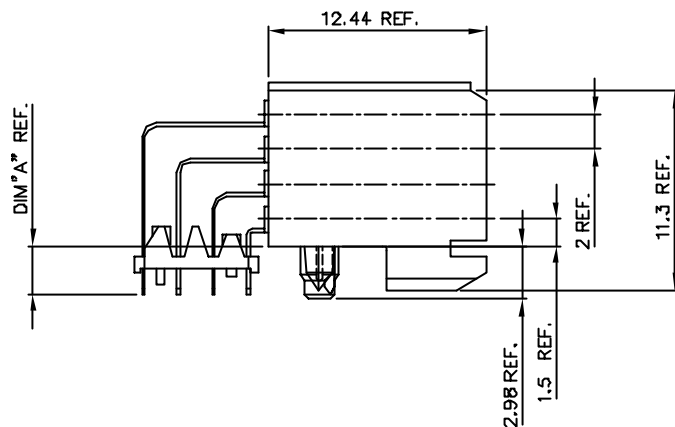


PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89037-X01/X01LF	1.6	2.73
89037-X11/X11LF	2.4	3.53



PRODUCT AFTER PC BOARD APPLICATION.

PC BOARD THICKNESS ±0.20
SEE TABLE

NOTES:

- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 PLATING SOLDER TAILS 2-8 μ m SnPb 90-97 OR 2-8 μ m PURE Sn
- 4 INDICATED HOLES ARE UNPLATED.
- 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
- 6 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
- 7 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 8 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

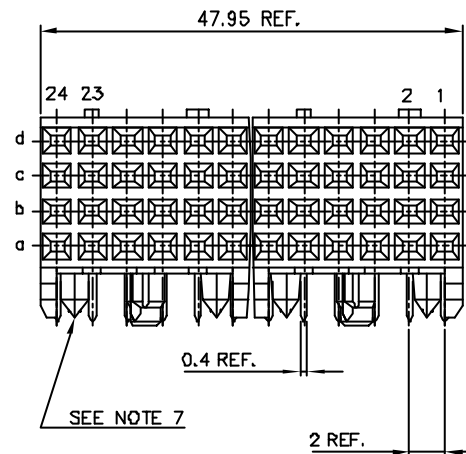
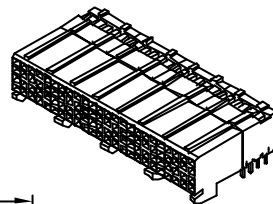
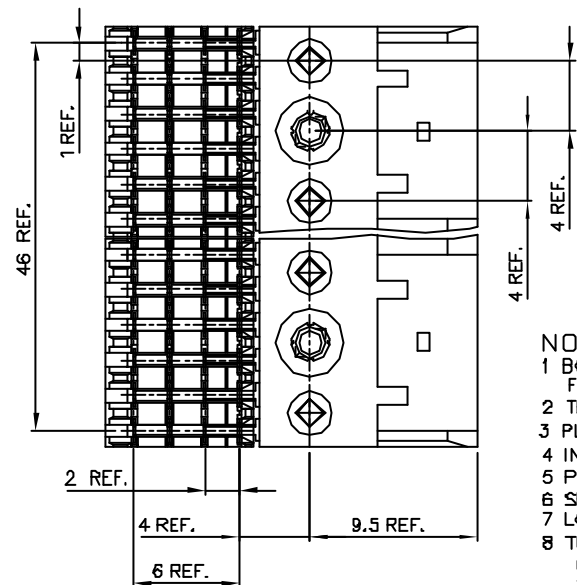
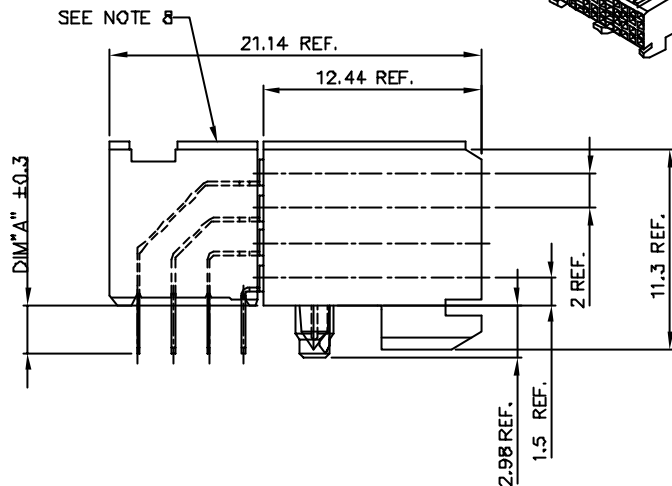
PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89037-1YZ/1YZLF	0.8 μ m GOLD	1.3 μ m Ni MIN.
89037-2YZ/2YZLF	2 μ m GOLD	1.3 μ m Ni MIN.
89037-3YZ/3YZLF	1.3 μ m GOLD	1.3 μ m Ni MIN.
89037-9YZ/9YZLF	0.8 μ m GXT	1.3 μ m Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER COPY		ELECTRONICS	
itr	ean no	dr	date	linear	projection	title	RA FEMALE SIGNAL
J	004-004	CU	041221			48 mm PRESS PEC	
D	H40305	008	040027	angles		product form	213
F	V70767	008	070530	dr	H4000000	size	213
F	V81480	008	090027	eng	H4000000	dwg no	213
G	V00078	008	000018	chr	S.Lee	scale	1 of 2
H	V00047	008	000030	appd	J.W.W.	8:1	
sheet	revision	J	J				
index	sheet	1	2				

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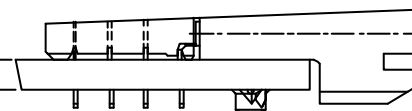
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PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89037-X02/X02LF	1.6	2.73
89037-X12/X12LF	2.4	3.53



PC BOARD THICKNESS ±0.20
SEE TABLE

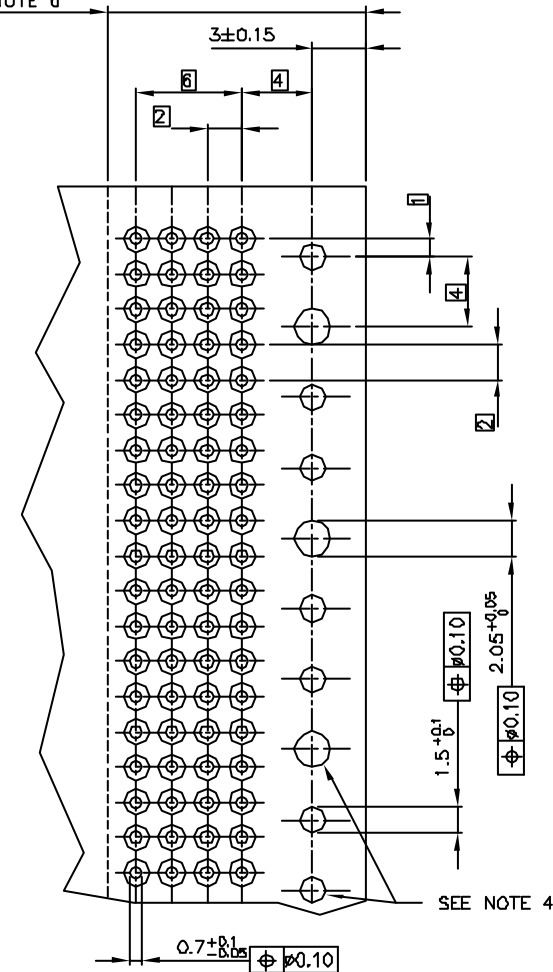
PRODUCT AFTER PC BOARD APPLICATION.



NOTES:

- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
- 3 PLATING SOLDER TAILS 2-8 μ m SnPb 90-97 OR 2-8 μ m PURE Sn
- 4 INDICATED HOLES ARE UNPLATED.
- 5 PRODUCT MARKING: PART NUMBER & BATCH ID.
- 6 SET BACK FOR PRESS BLOCK.
- 7 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
- 8 TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD
- 9 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-D08
- 10 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

14.64 REF. SEE NOTE 6



RECOMMENDED HOLE PATTERN,
COMPONENT SIDE.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89037-1YZ/1YZLF	0.8 μ m GOLD	1.3 μ m Ni MIN.
89037-2YZ/2YZLF	2 μ m GOLD	1.3 μ m Ni MIN.
89037-3YZ/3YZLF	1.3 μ m GOLD	1.3 μ m Ni MIN.
89037-9YZ/9YZLF	0.8 μ m GXT	1.3 μ m Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER COPY		ELECTRONICS	
itr	son no dr	date	linear	projection	title	RA FEMALE SIGNAL	www.dhanelectronics.com
j			angles		48 mm PRESS PEC		
			dr	0.45 mm	product form METRAL (mm)	code	213
			eng	P. Scholt	size dwg no	sheet	2 of
			chr	P. Scholt	scale	8:1	
			appl	0.45 mm			
sheet index	revision sheet						